

SOT915-2

plastic very thin fine-pitch ball grid array package; 373 balls;
top 120 lands; stackable; body 14 x 14 x 0.65 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	VFBGA373S
Package type industry code	VFBGA373S
Package style descriptive code	VFBGA (very thin fine-pitch ball grid array)
Package style suffix code	S (stackable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	7-3-2006

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		13.9	-	14	14.1	mm
E	package width		13.9	-	14	14.1	mm
A	seated height		[tbd]	-	1	1	mm
A ₂	package height		0.58	-	0.65	0.72	mm
n ₂	actual quantity of termination		-	-	373	-	



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2. Package outline

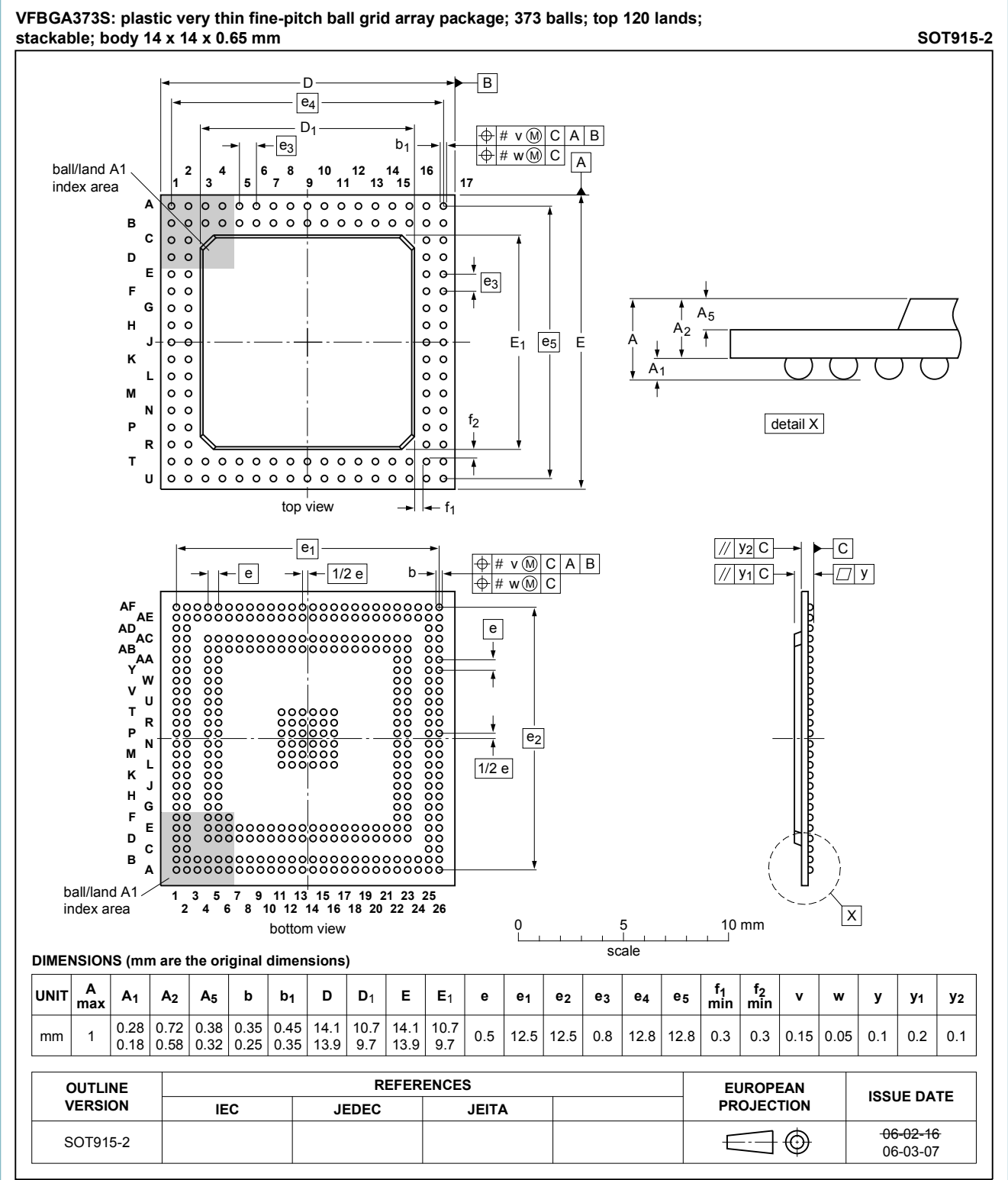


Fig. 1. Package outline VFBGA373S (SOT915-2)

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3. Soldering

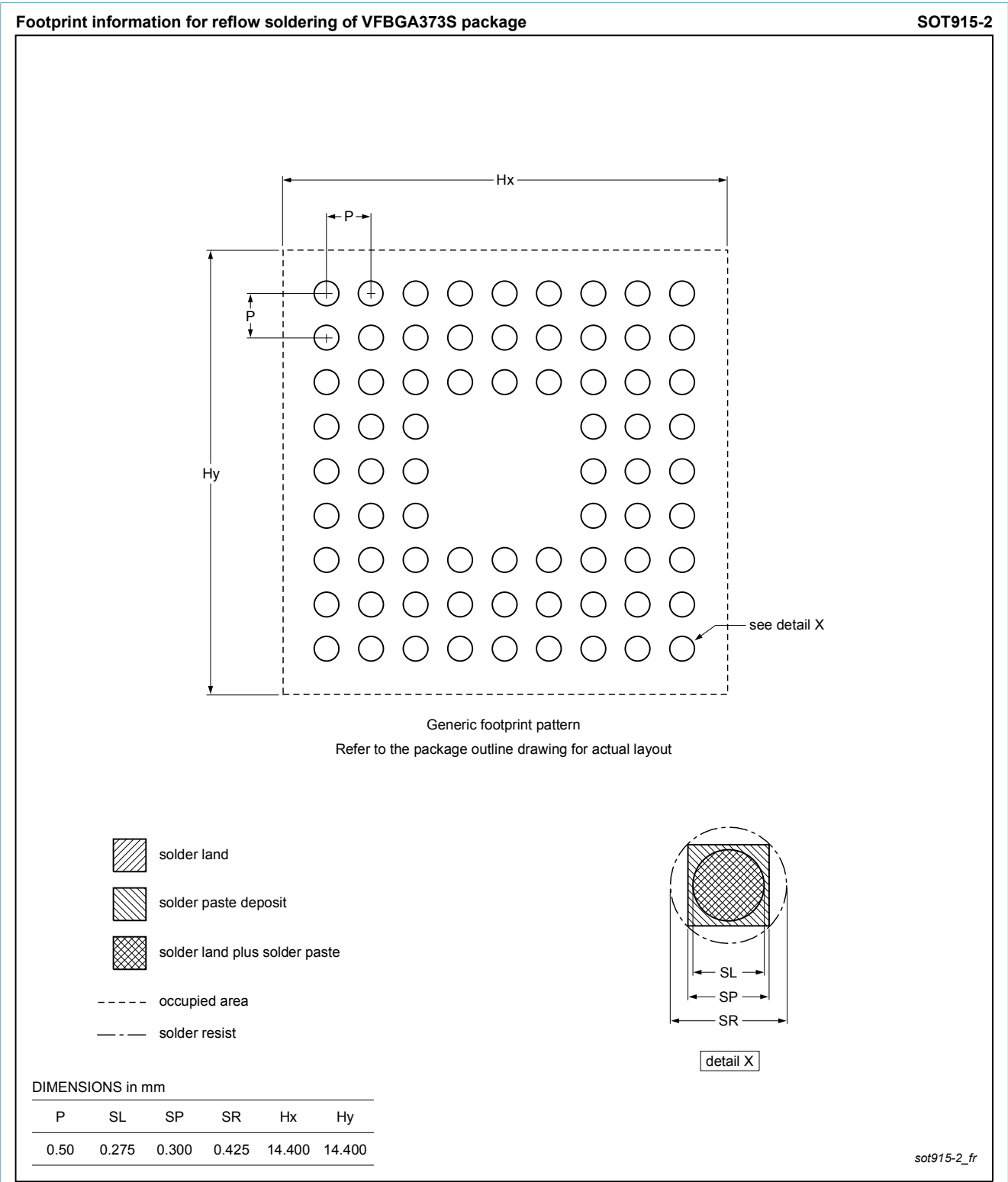


Fig. 2. Reflow soldering footprint for VFBGA373S (SOT915-2)

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4. Legal information

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